

## Bill of Materials

TI DESIGNS

TIDC-BLUETOOTH-SMART-KEYBOARD-MODULE

		Part				Manufacturer Part	Alternate	PCB
Item	Quantity	Reference	Value	Part Description	Manufacturer	Number	Part	Package
1	1	C2	DNM	CAPACITOR, DO NOT MOUNT, 0603, SMD			Nil	
				CAPACITOR, CERAMIC COG/NP0, 12pF, 50V,	MANUFACTURE	CAPACITOR_0402_12pF_C0		
2	2	C3 C4	12pF	-5%/+5%, -55DEGC/+125DEGC, 0402, SMD	R SELECTION	G/NP0_M_+/-5%_50V	Nil	0402
				CAPACITOR, CERAMIC X5R, 10uF, 6.3V, -				
3	2	C5 C18	10uF	20%/+20%, -55DEGC/+85DEGC, 0603, SMD	MURATA	GRM188R60J106ME47D	Nil	0603
				CAPACITOR, CERAMIC X7R, 100nF, 6.3V, -				
		C6 C7 C9 C10		10%/+10%, -55DEGC/+125DEGC, 0402,				
4	6	C22 C25	100nF	SMD	MURATA	GRM155R70J104KA01D	Nil	0402
				CAPACITOR, CERAMIC COG/NPO, 6.8pF,				
				50V, -0.25pF, +0.25pF, -				
5	1	C11	6.8pF	55DEGC/+125DEGC, 0402, SMD	MURATA	GRM1555C1H6R8CA01D	NII	0402
				CAPACITOR, CERAMIC COG/NPO, 1pF, 50V, -				
				0.25pF/ +0.25pF, -55DEGC/+125DEGC,				
6	2	C12 C13	1pF	0402, SMD	MURATA	GRM1555C1H1R0CA01D	Nil	0402
				CAPACITOR, CERAMIC COG/NP0, 1.2pF,				
				50V, -0.1pF/ +0.1pF, -55DEGC/+125DEGC,				
7	2	C14 C16	1.2pF	0402, SMD	MURATA	GRM1555C1H1R2BA01D	Nil	0402
			•					
				CAPACITOR, CERAMIC COG/NPO, 12pF, 50V,				
8	1	C15	12pF	-5%/+5%, -55DEGC/+125DEGC, 0402, SMD	MURATA	GRM1555C1H120JA01D	Nil	0402

				CAPACITOR, CERAMIC X7R, 100nF, 25V, -				
				10%/+10%, -55DEGC/+125DEGC, 0603,				
9	1	C17	100nF	SMD	MURATA	GRM188R71E104KA01D	Nil	0603
		C19 C20 C26		CAPACITOR, CERAMIC, N/A VALUE, -	Manufacturer	CAPACITOR 0402 DNM N		
10	4	C27	DNM	55DEGC/+125DEGC, 0402, SMD	selection	 /A_M	Nil	0402
				CAPACITOR, CERAMIC, 1uF, -20%+80%,				
11	1	C23	1uF	Y5V, 6.3V, 0402, SMD	MURATA	GRM155F50J105ZE01D	Nil	0402
			BLM18HE	FILTER, EMI, 1500@100MHz, -				
12	1	FL1	152SN1	55DEGC/+125DEGC, 0603, SMD	MURATA	BLM18HE152SN1D	Nil	0603
				INDUCTOR, CHIP, 10uH, -20%/+20%, 0.11A,				
13	1	L1	10uH	-40DEGC/+85DEGC, 0805, SMD	TAIYO YUDEN	CKS2125100M-T	Nil	0805
				INDUCTOR, CHIP, 2.4nH, -0.3nH/+0.3nH,				
14	2	L2 L3	2.4nH	0.3A, -55DEGC/+125DEGC, 0402, SMD	MURATA	LQG15HN2N4S02D	Nil	0402
				INDUCTOR, CHIP, 2nH, -0.3nH/ +0.3nH,				
15	1	L4	2nH	0.3A, -55DEGC/+125DEGC, 0402, SMD	MURATA	LQG15HS2N0S02D	Nil	0402
				RESISTOR, THICK FILM, 100k, -1%/+1%,		RESISTOR_0402_100k_+/-		
				0.063W, 50V, -55DEGC/+155DEGC, 0402,	MANUFACTURE	1%_50V_0.063W_M_+/-		
16	1	R4	100k	SMD	R SELECTION	100PPM	Nil	0402
				RESISTOR, JUMPER, -55DEGC/+155DEGC,				
17	1	R20	0	0402, SMD	KOA SPEER	RK73Z1ETTP	Nil	0402
			CC2650F1	IC, DIGITAL, 2.4GHZ SIMPLELINK WIRELESS	TEXAS			
18	1	U1	28RGZ	MCU, PITCH 0,5MM, QFN48, SMD	INSTRUMENTS	CC2650F128RGZT	Nil	QFN48
			32.768kH	CRYSTAL, RESONATOR, 32.768kHz, -				
19	1	Y1	Z	20PPM/+20PPM, -40DEGC/+85DEGC, SMD	EPSON	FC-135 32.7680KA-AG0	Nil	
				CRYSTAL, OSCILATOR, 24MHz, -				
20	1	Y3	24MHz	40DEGC/+85DEGC, SMD	Epson Toyocom	TSX-3225 24MHz	Nil	

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